



**DOCUMENT TITLE:
PACKAGE OUTLINE DRAWING, 564L TBGA 35X35X1.65MM**

DOC ID # 21-0371

NEW REV: A

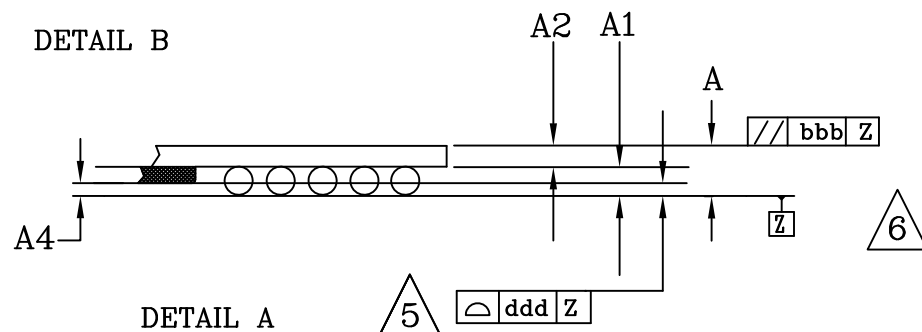
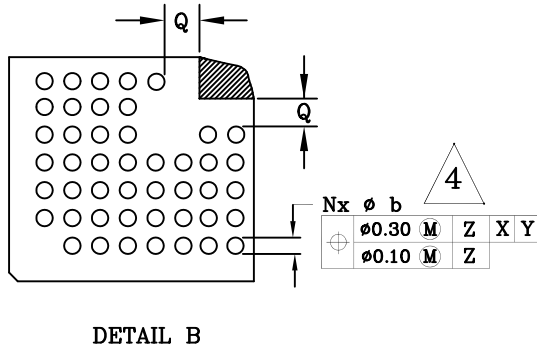
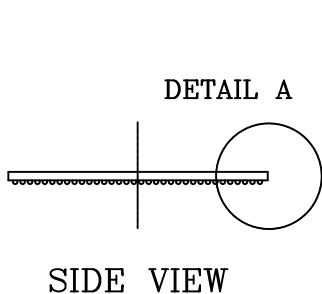
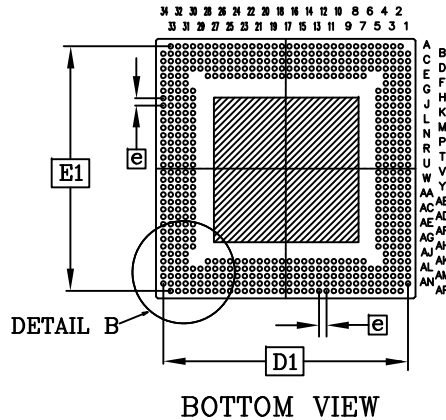
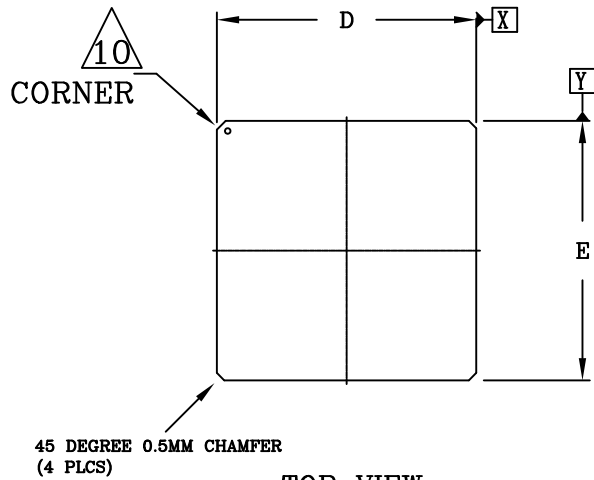
ECN#: HQ-08-5761

EFFECTIVE DATE: 07/01/08

ORIGINATOR: JEFF WALKER

MOST RECENT CHANGES

FROM	TO
DALLAS DOCUMENT CONTROL SYSTEM DOC ID# 56-G6038-007 LOGO-DALLAS/MAXIM	INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL LOGO-MAXIM



DIMENSIONAL REFERENCES			
REF.	MIN.	NOM.	MAX.
A	1.45	1.65	1.85
A1	0.40	0.50	0.60
A2	1.05	1.15	1.25
A4	0.10		
D	34.80	35.00	35.20
D1		33.00 (BSC.)	
E	34.80	35.00	35.20
E1		33.00 (BSC.)	
b	0.50	0.63	0.75
M		34	
N		564	
bbb			0.25
ddd		0.20	
e		1.00 TYP.	
Q	0.25		

NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS.
- "e" REPRESENTS THE BASIC SOLDER BALL GRID PITCH.
- "M" REPRESENTS THE BASIC SOLDER BALL MATRIX SIZE, AND SYMBOL "N" IS THE MAXIMUM ALLOWABLE NUMBER OF BALLS AFTER DEPOPULATING.
- "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER AFTER REFLOW PARALLEL TO PRIMARY DATUM [Z].
- DIMENSION "ddd" IS MEASURED PARALLEL TO PRIMARY DATUM [Z].
- PRIMARY DATUM [Z] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- PACKAGE SURFACE SHALL BE BLACK INK.
- CAVITY DEPTH VARIES WITH DIE THICKNESS.
- SUBSTRATE MATERIAL BASE IS COPPER.
- 45 DEG. 0.45 MM CHAMFER CORNER AND WHITE SPOT FOR PIN 1 IDENTIFICATION.
- ENCAPSULANT SIZE MAY VARY WITH DIE SIZE.
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M 1994
- CONFORMS TO JEDEC MO-149F, EXCEPT "b" DIMENSION.

MAXIM

PROPRIETARY INFORMATION

PACKAGE OUTLINE
564L TBGA 35x35x1.65mm

APPROVAL	DOCUMENT CONTROL NO. 21-0371	REV. A	1/1
----------	---------------------------------	-----------	-----

-DRAWING NOT TO SCALE-

REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	ECN# HQ-08-5761. INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL. LOGO-MAXIM	07/01/08	JW



TITLE: PACKAGE OUTLINE DRAWING, 564L TBGA 35X35X1.65MM

DOCUMENT I.D.
21-0371

REVISION
A

PAGE
3